FLIP CHIP BONDER AND FLIP CHIP BONDING METHOD

ABSTRACT

Provided is a flip chip bonder including: a pickup flipping collet (30) configured to flip a chip (20); and a bonding tool (50) configured to receive the chip (20) flipped by the pickup flipping collet (30) from the pickup flipping collet (30) and to bond the received chip (20) to a circuit board (65). The pickup flipping collet (30) includes a cooling channel through which cooling air flows to cool the pickup flipping collet (30). Thus, bonding time can be reduced without lowering bonding quality.

FIGURE 1